



DT2636-04S

4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

Features

- IEC 61000-4-2 (ESD): Air ±20kV, Contact ±18kV
- 4 Channels of ESD Protection
- Low Channel Input Capacitance of 0.65pF Typical
- Typically Used at High Speed Ports such as USB 2.0, IEEE1394, Serial ATA, DVI, HDMI, PCI
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

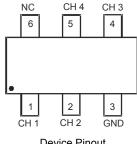
Mechanical Data

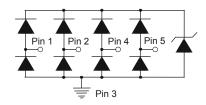
- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.006 grams (approximate)





Top View





Device Pinout

Device Schematic

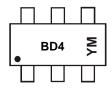
Ordering Information (Note 4)

Part Number	Case	Packaging
DT2636-04S-7	SOT363	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



BD4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013)M = Month (ex: 9 = September)

Date Code Key

Year	2013	3	2014		2015	20	16	2017		2018		2019
Code	Α		В		С)	E		F		G
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	I _{PP}	6.5	Α	8/20µs, From CH to GND
Peak Pulse Current	I _{PP}	6.5	Α	8/20µs, From GND to CH
Peak Pulse Power	P _{PP}	60	W	8/20µs, From CH to GND
ESD Protection – Contact Discharge	V _{ESD_Contact}	±18	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V _{ESD_Air}	±20	kV	Standard IEC 61000-4-2
Operating Temperature	T _{OP}	-55 to +85	°C	_
Storage Temperature	T _{STG}	-55 to +150	°C	_

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P_{D}	200	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{ hetaJA}$	625	°C/W

Electrical Characteristics (@T_A = +25°C, unless otherwise specified)

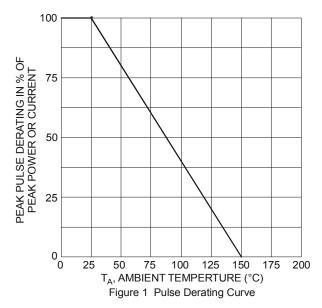
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Standoff Voltage	V_{RWM}	_	_	5.5	V	_
Channel Leakage Current (Note 6, 7)	I _R	_	1	10	nA	V _R = 2.5V
Reverse Breakdown Voltage	V _{BR}	7.0	_	9.5	V	I _R = 1mA, from CH to GND
Clamping Voltage, Positive Transients	V _{CL1}	_	6.8	_	V	I_{PP} = 1A, t_p = 8/20 μ s
Clamping Voltage, Positive Transients	V _{CL1}	_	9	_	V	$I_{PP} = 5A, t_p = 8/20 \mu s$
Clamping Voltage, Negative Transients	V _{CL2}	_	1.5	_	V	I_{PP} = 1A, t_p = 8/20 μ s
Forward Voltage	VF	_	0.7	_	V	I _F = 1mA, GND to CH
Dynamic Resistance	R _{DIFF}	_	0.4	_	Ω	I_{PP} = 1A, t_p = 8/20 μ s, CH to GND
Dynamic Resistance	R _{DIFF-R}	_	0.45	_	Ω	TLP, 20A, tp = 100 ns, CH to GND
Dynamic Resistance	R _{DIFF-F}	_	0.2	_	Ω	TLP, 20A, tp = 100 ns, GND to CH
CII to CND Consoitones	C _(CH-GND)	_	0.75	_	pF	V _(CH-GND) = 0V, f = 1MHz
CH to GND Capacitance		_	0.65	0.9	pF	V _(CH-GND) = 2.5V, f = 1MHz
Delta Ссн	Сснмах- Сснмім	_	0.04	_	pF	C _{CHMAX} -C _{CHMIN}

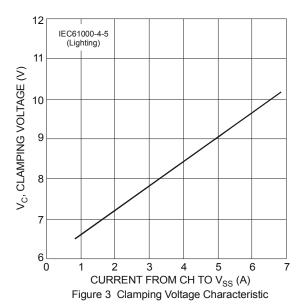
Notes:

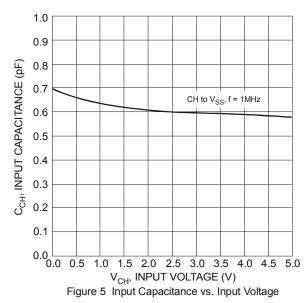
^{5.} Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

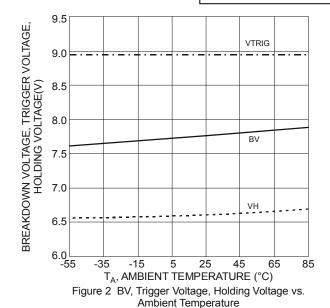
^{6.} Short duration pulse test used to minimize self-heating effect.
7. Measured from pin 1, 2, 4 and 5 to GND.











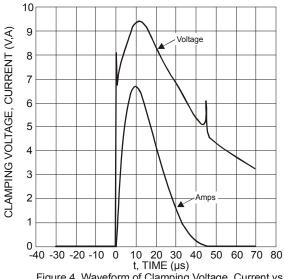
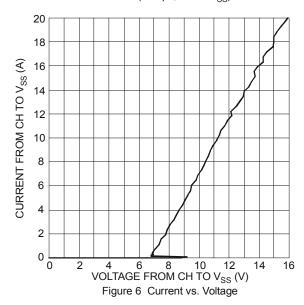


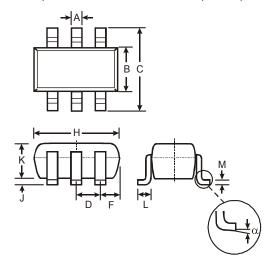
Figure 4 Waveform of Clamping Voltage, Current vs. Time (8/20 μ s, CH to V $_{\rm SS}$)





Package Outline Dimensions

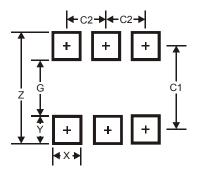
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT363					
Dim	Min	Max	Тур		
Α	0.10	0.30	0.25		
В	1.15	1.35	1.30		
U	2.00	2.20	2.10		
D	0.65 Typ				
F	0.40	0.45	0.425		
Н	1.80	2.20	2.15		
7	0	0.10	0.05		
K	0.90	1.00	1.00		
Ь	0.25	0.40	0.30		
М	0.10	0.22	0.11		
α	0°	8°	-		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



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